TIBPAL16L8-5C, TIBPAL16R4-5C, TIBPAL16R6-5C, TIBPAL16R8-5C TIBPAL16L8-7M, TIBPAL16R4-7M, TIBPAL16R6-7M, TIBPAL16R8-7M HIGH-PERFORMANCE IMPACT-X™ PAL® CIRCUITS

SRPS011D - D3359, OCTOBER 1989 - REVISED SEPTEMBER 1992

High-Performance Operation:

f_{max} (no feedback)

TIBPAL16R'-5C Series . . . 125 MHz Min

TIBPAL16R' -7M Series . . . 100 MHz Min

f_{max} (internal feedback)

TIBPAL16R' -5C Series . . . 125 MHz Min

TIBPAL16R' -7M Series . . . 100 MHz Min

f_{max} (external feedback)

TIBPAL16R' -5C Series . . . 117 MHz Min

TIBPAL16R' -7M Series . . . 74 MHz Min

Propagation Delay

TIBPAL16L8-5C Series . . . 5 ns Max

TIBPAL16L8-7M Series . . . 7 ns Max

TIBPAL16R' -5C Series

(CLK-to-Q) . . . 4 ns Max

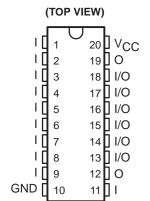
TIBPAL16R '-7M Series

(CLK-to-Q) . . . 6.5 ns Max

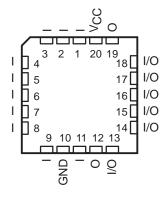
- Functionally Equivalent, but Faster than, Existing 20-Pin PLDs
- Preload Capability on Output Registers Simplifies Testing
- Power-Up Clear on Registered Devices (All Register Outputs are Set Low, but Voltage Levels at the Output Pins Go High)
- Package Options Include Both Plastic and Ceramic Chip Carriers in Addition to Plastic and Ceramic DIPs
- Security Fuse Prevents Duplication

DEVICE	I INPUTS	3-STATE O OUTPUTS	REGISTERED Q OUTPUTS	I/O PORT S
'PAL16L8	10	2	0	6
'PAL16R4	8	0	4 (3-state buffers)	4
'PAL16R6	8	0	6 (3-state buffers)	2
'PAL16R8	8	0	8 (3-state buffers)	0

TIBPAL16L8' C SUFFIX . . . J OR N PACKAGE M SUFFIX . . . J PACKAGE



TIBPAL16L8'
C SUFFIX . . . FN PACKAGE
M SUFFIX . . . FK PACKAGE
(TOP VIEW)



Pin assignments in operating mode

description

These programmable array logic devices feature high speed and functional equivalency when compared with currently available devices. These IMPACT-XTM circuits combine the latest Advanced Low-Power Schottky technology with proven titanium-tungsten fuses to provide reliable, high-performance substitutes for conventional TTL logic. Their easy programmability allows for quick design of custom functions and typically results in a more compact circuit board.

The TIBPAL16' C series is characterized from 0°C to 75°C. The TIBPAL16' M series is characterized for operation over the full military temperature range of –55°C to 125°C.

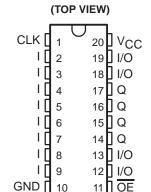
These devices are covered by U.S. Patent 4,410,987. IMPACT-X is a trademark of Texas Instruments Incorporated. PAL is a registered trademark of Advanced Micro Devices Inc.



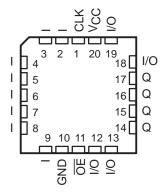
TIBPAL16R4-5C, TIBPAL16R6-5C, TIBPAL16R8-5C TIBPAL16R4-7M, TIBPAL16R6-7M, TIBPAL16R8-7M HIGH-PERFORMANCE *IMPACT-X* TM *PAL*® CIRCUITS

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TIBPAL16R4'
C SUFFIX . . . J OR N PACKAGE
M SUFFIX . . . J PACKAGE

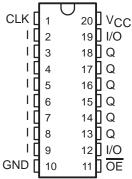


TIBPAL16R4'
C SUFFIX . . . FN PACKAGE
M SUFFIX . . . FK PACKAGE
(TOP VIEW)

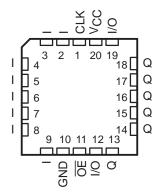


TIBPAL16R6'
C SUFFIX ... J OR N PACKAGE
M SUFFIX ... J PACKAGE

(TOP VIEW)

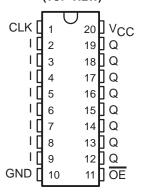


TIBPAL16R6'
C SUFFIX . . . FN PACKAGE
M SUFFIX . . . FK PACKAGE
(TOP VIEW)

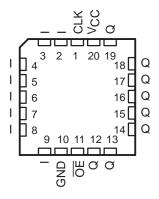


TIBPAL16R8'
C SUFFIX . . . J OR N PACKAGE
M SUFFIX . . . J PACKAGE

(TOP VIEW)



TIBPAL16R8'
C SUFFIX . . . FN PACKAGE
M SUFFIX . . . FK PACKAGE
(TOP VIEW)

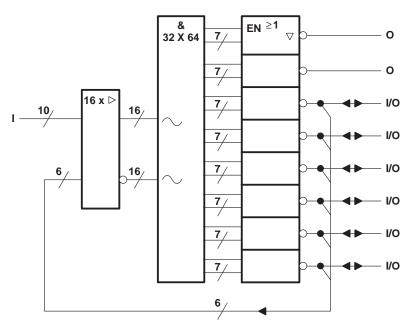


Pin assignments in operating mode

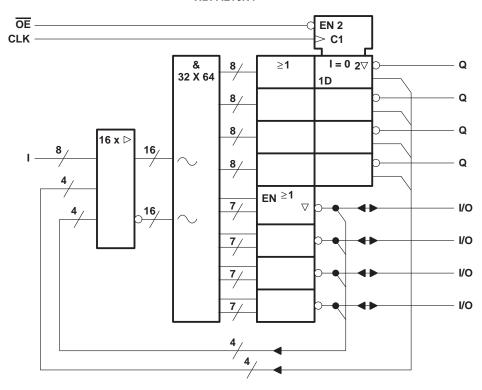


functional block diagrams (positive logic)

TIBPAL16L8'



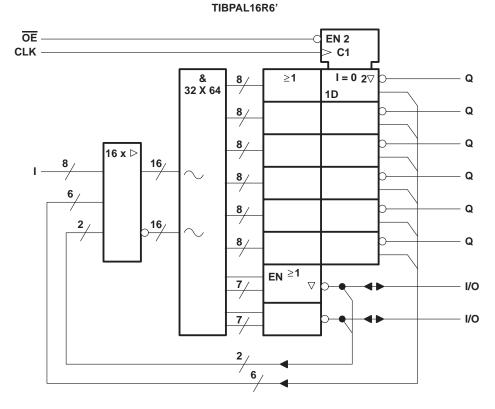
TIBPAL16R4'



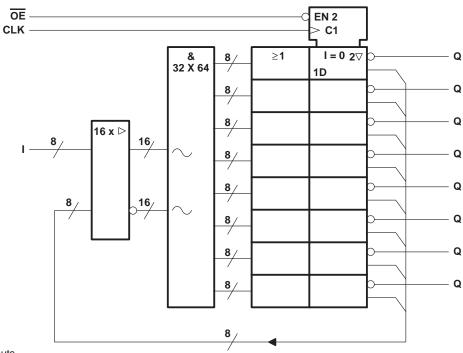
✓ denotes fused inputs



functional block diagrams (positive logic)

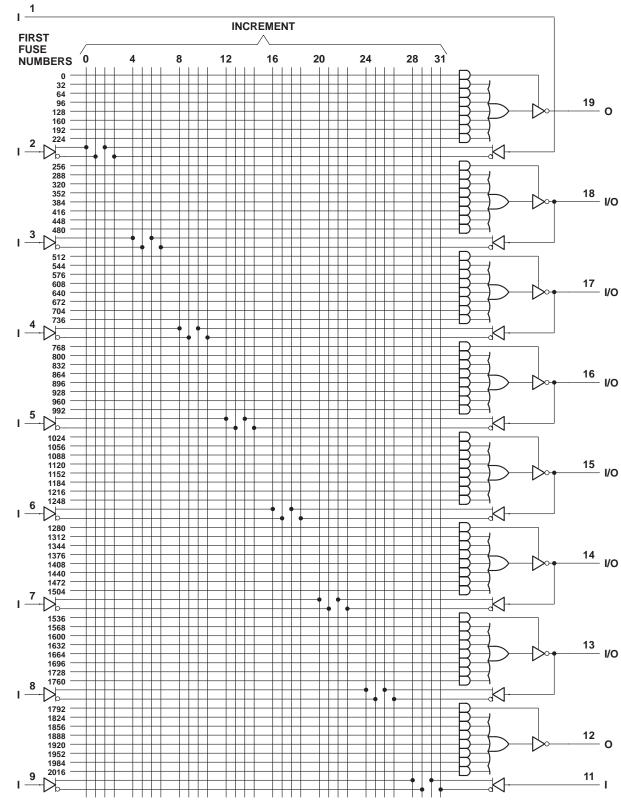


TIBPAL16R8'



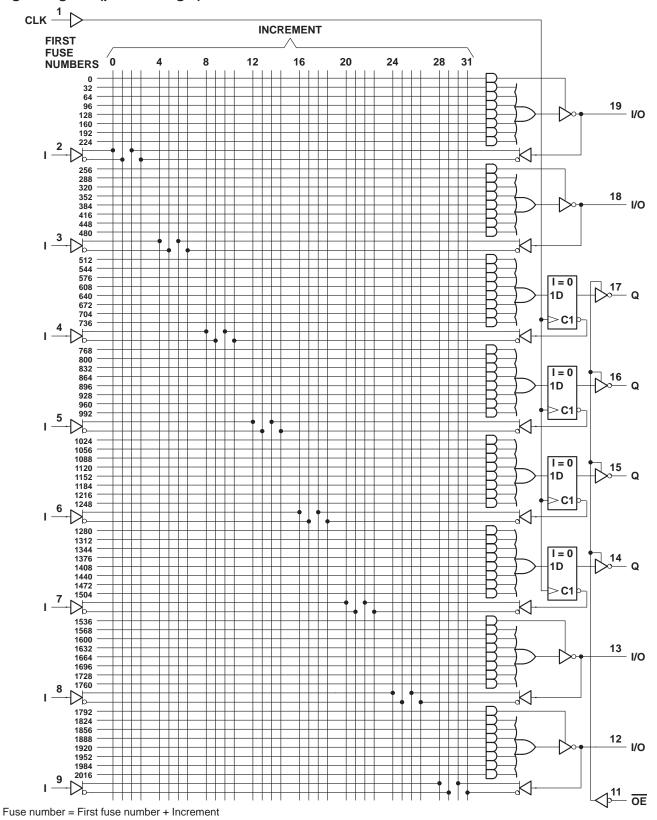
✓ denotes fused inputs



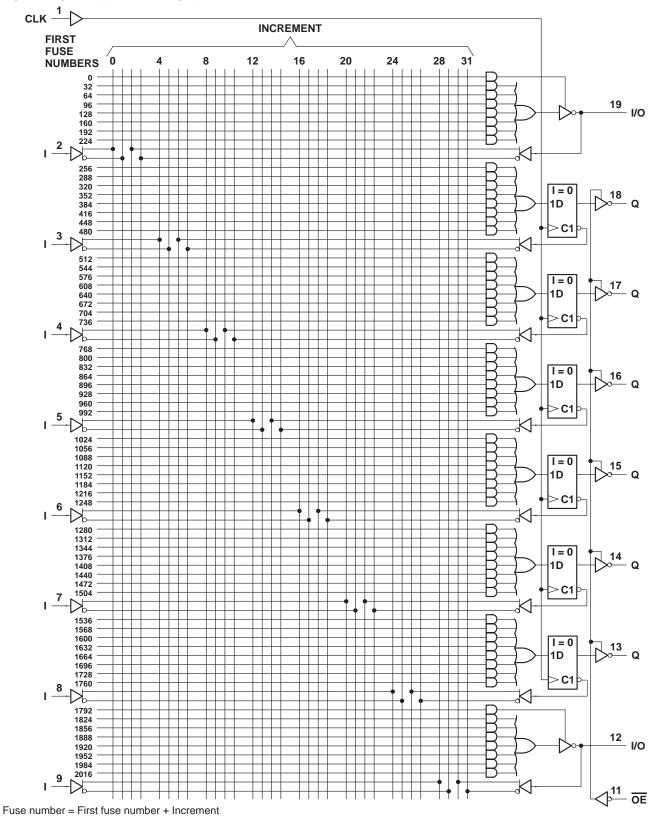


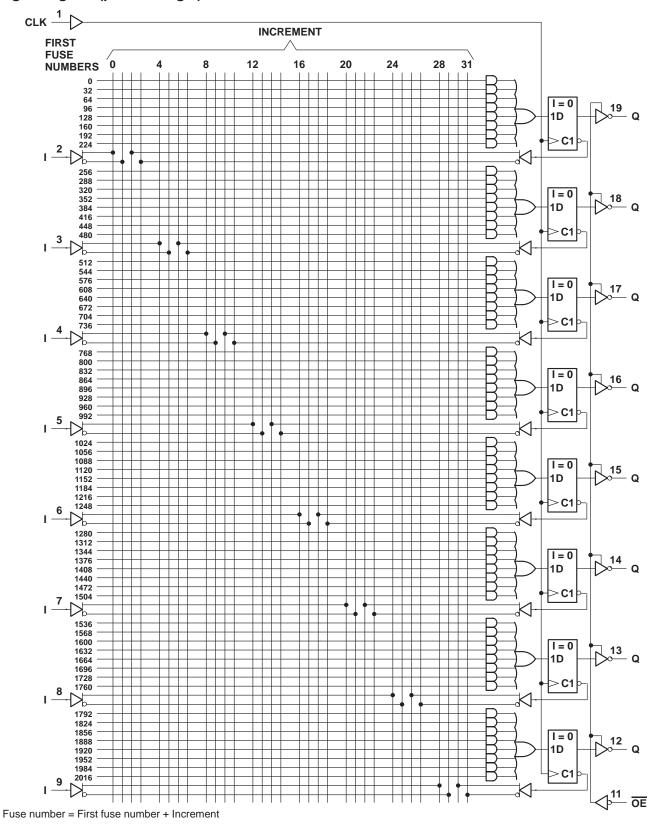
Fuse number = First fuse number + Increment













absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	0°C to 75°C
Storage temperature range	-65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage (see Note 2)	2		5.5	V
VIL	Low-level input voltage (see Note 2)			0.8	V
ІОН	High-level output current			-3.2	mA
lOL	Low-level output current			24	mA
TA	Operating free-air temperature	0	25	75	°C

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.

electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS	3	MIN	TYP [†]	MAX	UNIT
VIK	$V_{CC} = 4.75 \text{ V},$	$I_{I} = -18 \text{ mA}$			-0.8	-1.5	V
VOH	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3.2 \text{ mA}$		2.4	2.7		V
VOL	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 24 \text{ mA}$			0.3	0.5	V
IOZH [‡]	V _{CC} = 5.25 V,	V _O = 2.7 V				100	μΑ
I _{OZL} ‡	V _{CC} = 5.25 V,	$V_0 = 0.4 V$				-100	μΑ
lį	V _{CC} = 5.25 V,	V _I = 5.5 V				100	μΑ
I _{IH} ‡	V _{CC} = 5.25 V,	V _I = 2.7 V				25	μΑ
I _{IL} ‡	V _{CC} = 5.25 V,	V _I = 0.4 V				-250	μΑ
IOS§	V _{CC} = 5.25 V,	V _O = 0.5 V		-30	-70	-130	mA
lcc	V _{CC} = 5.25 V,	$V_I = 0$,	Outputs open			180	mA
Ci	f = 1 MHz,	V _I = 2 V	·		8.5		pF
Co	f = 1 MHz,	V _O = 2 V			10		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM		TO (OUTPUT)	TEST	TIBPAL16	L8-5CFN		L16L8-5CJ L16L8-5CN	UNIT
	(INPUT)		(OUTPUT)	CONDITIONS	MIN	MAX	MIN	MAX	
	I, I/O	O, I/O	with up to 4 outputs switching		1.5	5	1.5	5	
^t pd	I, I/O	O, I/O	with more than 4 outputs switching	R1 = 200 Ω , R2 = 200 Ω ,	1.5	5	1.5	5.5	ns
t _{en}	I, I/O		O, I/O	See Figure 8	2	7	2	7	ns
^t dis	I, I/O		O, I/O		2	7	2	7	ns



[‡]I/O leakage is the worst case of IOZL and I_{IL} or IOZH and I_{IH}, respectively.

Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. Vo is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

TIBPAL16R4-5C, TIBPAL16R6-5C HIGH-PERFORMANCE *IMPACT-X™ PAL®* CIRCUITS

SRPS011D - D3359, OCTOBER 1989 - REVISED SEPTEMBER 1992

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	0°C to 75°C
Storage temperature range	-65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.75	5	5.25	V
VIH	High-level input voltage (see Note 2)				5.5	V
V _{IL}	Low-level input voltage (see Note 2)				0.8	V
IOH	High-level output current				-3.2	mA
loL	Low-level output current				24	mA
fclock	Clock frequency		0		125	MHz
	Pulse duration, clock	High	4			ns
t _W	ruise duration, clock	Low	4			113
t _{su}	Setup time, input or feedback before clock↑		4.5			ns
th	Hold time, input or feedback after clock↑		0			ns
TA	Operating free-air temperature		0	25	75	°C

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.

electrical characteristics over recommended operating free-air temperature range

PARA	AMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 4.75 V,	$I_{I} = -18 \text{ mA}$			-0.8	-1.5	V
Vон		$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3.2 \text{ mA}$		2.4	2.7		V
VOL		$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 24 \text{ mA}$			0.3	0.5	V
l _{OZH} ‡		$V_{CC} = 5.25 \text{ V},$	V _O = 2.7 V				100	μΑ
l _{OZL} ‡		$V_{CC} = 5.25 \text{ V},$	V _O = 0.4 V				-100	μΑ
II		$V_{CC} = 5.25 \text{ V},$	V _I = 5.5 V				100	μΑ
I _{IH} ‡		V _{CC} = 5.25 V,	V _I = 2.7 V				25	μΑ
I _{IL} ‡		V _{CC} = 5.25 V,	V _I = 0.4 V				-250	μΑ
IOS§		V _{CC} = 5.25 V,	V _O = 0.5 V		-30	-70	-130	mA
Icc		V _{CC} = 5.25 V,	$V_{I} = 0$,	Outputs open			200	mA
C.	I	f = 1 MHz,	V _I = 2 V			7		pF
C _i CLK/OE		1 = 1 1011 12,	V = 2 V			5		ρı
C	I/O	f = 1 MHz,	V _O = 2 V	_		10		pF
Co	Q	i = i ivi⊓∠,	v () = 2 v			7		рг

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		TIBPAL16R4-5CFN TIBPAL16R6-5CFN			TIBPAL16R4-5CFN TIBPAL16R6- TIBPAL16R6-5CFN TIBPAL16R4-5			TIBPAL16R4-5CJ TIBPAL16R6-5CJ TIBPAL16R4-5CN TIBPAL16R6-5CN			UNIT
				MIN	TYP [†]	MAX	MIN	TYP [†]	MAX				
	withou	t feedback		125			125						
$f_{max}\P$	with internal feedbac	k (counter configuration)		125			125			MHz			
	with exter	nal feedback		117			111						
tpd	CLK↑	Q		1.5		4	1.5		4.5	ns			
t _{pd}	CLK↑	Internal feedback	R1 = 200 Ω ,			3.5			3.5	ns			
t _{pd}	I, I/O	I/O	$R2 = 200 \Omega$,	1.5		5	1.5		5	ns			
t _{en}	ŌE↓	Q	See Figure 8	1.5		6	1.5		6	ns			
^t dis	ŌE↑	Q		1		6.5	1		7	ns			
t _{en}	I, I/O	I/O		2		7	2		7	ns			
t _{dis}	I, I/O	I/O		2		7	2		7	ns			
t _r					1.5			1.5		ns			
t _f					1.5			1.5		ns			
tsk(o)#	Skew between	registered outputs			0.5	·		0.5		ns			

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



 $[\]ddagger$ I/O leakage is the worst case of IOZL and I_{IL} or IOZH and I_{IH}, respectively.

[§] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. Vo is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

[¶] See 'fmax Specification' near the end of this data sheet.

[#] t_{Sk(0)} is the skew time between registered outputs.

TIBPAL16R8-5C HIGH-PERFORMANCE *IMPACT-X™ PAL®* CIRCUITS

SRPS011D - D3359, OCTOBER 1989 - REVISED SEPTEMBER 1992

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	0°C to 75°C
Storage temperature range	-65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.75	5	5.25	V
VIH	High-level input voltage (see Note 2)				5.5	V
V _{IL}	Low-level input voltage (see Note 2)				0.8	V
ІОН	High-level output current				-3.2	mA
loL	Low-level output current				24	mA
fclock	Clock frequency		0		125	MHz
	Dulas duration alask	High	4			ns
t _W	Pulse duration, clock	Low	4			115
t _{su}	Setup time, input or feedback before clock↑		4.5			ns
th	Hold time, input or feedback after clock↑		0			ns
TA	Operating free-air temperature		0	25	75	°C

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.



electrical characteristics over recommended operating free-air temperature range

PARAMETER	TES	T CONDITIONS	TIBPA	TIBPAL16R8-5CFN		TIBPAL16R8-5CJ TIBPAL16R8-5CN			UNIT
TANAMETER	120	TOORDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	Oitii
VIK	$V_{CC} = 4.75 V$,	$I_{I} = -18 \text{ mA}$		-0.8	-1.5		-0.8	-1.5	V
VOH	$V_{CC} = 4.75 V$,	$I_{OH} = -3.2 \text{ mA}$	2.4	2.7		2.4	2.7		V
V _{OL}	$V_{CC} = 4.75 V$,	I _{OL} = 24 mA		0.3	0.5		0.3	0.5	V
lozh	$V_{CC} = 5.25 \text{ V},$	$V_0 = 2.7 \text{ V}$			100			100	μΑ
I _{OZL}	$V_{CC} = 5.25 \text{ V},$	V _O = 0.4 V			-100			-100	μΑ
IĮ	$V_{CC} = 5.25 \text{ V},$	V _I = 5.5 V			100			100	μΑ
lн	$V_{CC} = 5.25 \text{ V},$	V _I = 2.7 V			25			25	μΑ
I _{IL}	$V_{CC} = 5.25 \text{ V},$	V _I = 0.4 V			-250			-250	μΑ
los [‡]	$V_{CC} = 5.25 \text{ V},$	V _O = 0.5 V	-30	-70	-130	-30	-70	-130	mA
Icc	V _{CC} = 5.25 V,	V _I = 0, Outputs open			180			180	mA
	£ 4 MIL-	W- 0.W		8.5			6.5		nE
CLK/OE	f = 1 MHz,	V _I = 2 V		7.5			5.5		pF
Co	f = 1 MHz,	V _O = 2 V		10			8		pF

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM TO		TEST CONDITIONS	TIBPAL16R8-5CFN			TIBPAL16R8-5CJ TIBPAL16R8-5CN			UNIT	
	(INPUT)	(OUTPUT)		CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	
	without feedback				125			125			MHz
f _{max} §	with internal feedback (counter configuration)				125			125			
	with external feedback				117			111			
	CLK↑	Q	with up to 4 outputs switching	R1 = 200 Ω,	1.5		4	1.5		4	
^t pd	CLK↑	Q	with more than 4 outputs switching	R2 = 200Ω , See Figure 8	1.5		4	1.5		4.5	ns
t_{pd} ¶	CLK↑	Internal feedback					3.5			3.5	ns
t _{en}	OE↓		Q		1.5		6	1.5		6	ns
t _{dis}	ŌE↑		Q		1		6.5	1		7	ns
t _r						1.5			1.5		ns
t _f						1.5	·		1.5		ns
tsk(o)#	Ske	ew betwee	en outputs			0.5			0.5		ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. V_O is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

[§] See 'fmax Specification' near the end of this data sheet.

This parameter is calculated from the measured f_{max} with internal feedback in a counter configuration (see Figure 2 for illustration).

[#] t_{Sk(0)} is the skew time between registered outputs.

TIBPAL16L8-7M, TIBPAL16R4-7M, TIBPAL16R6-7M, TIBPAL16R8-7M HIGH-PERFORMANCE $IMPACT-X^{TM}$ PAL^{\oplus} CIRCUITS

SRPS011D - D3359, OCTOBER 1989 - REVISED SEPTEMBER 1992

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	-55°C to 125°C
Storage temperature range	-65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	V
VIH	High-level input voltage (see Note 2)		2		5.5	V
V _{IL}	Low-level input voltage (see Note 2)				0.8	V
loh	High-level output current				-2	mA
lOL	Low-level output current				12	mA
f _{clock} †	Clock frequency		0		100	MHz
. +	Dulan danafan alaul	High	5			ns
t _W †	Pulse duration, clock	Low	5			115
t _{su} †	Setup time, input or feedback before clock↑		7			ns
t _h †	Hold time, input or feedback after clock↑					ns
TA	Operating free-air temperature				125	°C

[†] f_{clock}, t_w, t_{su}, and t_h do not apply to TIBPAL16L8'

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.



TIBPAL16L8-7M, TIBPAL16R4-7M, TIBPAL16R6-7M, TIBPAL16R8-7M HIGH-PERFORMANCE IMPACT-X™ PAL® CIRCUITS

SRPS011D - D3359, OCTOBER 1989 - REVISED SEPTEMBER 1992

electrical characteristics over recommended operating free-air temperature range

PARAMETER			TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-0.8	-1.5	V	
VOH		V _{CC} = 4.5 V,	I _{OH} = −2 mA		2.4	2.7		V	
VOL		V _{CC} = 4.5 V,	I _{OL} = 12 mA			0.25	0.5	V	
lozh	0, Q outputs	V _{CC} = 5.5 V,	V- 27V				20		
IOZH	I/O ports	VCC = 5.5 V,	$V_0 = 2.7 \text{ V}$				100	μΑ	
lozL	0, Q outputs	V _{CC} = 5.5 V,	V _O = 0.4 V	Vo = 0.4 V			-20	μА	
I.OZL	I/O ports	VCC = 0.0 v,	VO = 0.4 V				-250	μΛ	
Ц		$V_{CC} = 5.5 \text{ V},$	V _I = 5.5 V				1	mA	
Iн	I/O ports	V _{CC} = 5.5 V,	V _I = 2.7 V	\/ı - 2.7.\/			100	μА	
יור	All others	VCC = 0.0 V,	V - 2.7 V				25	μΛ	
I _{IL}		$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V				-250	μΑ	
los [‡]		$V_{CC} = 5.5 V$,	V _O = 0.5 V		-30	-70	-130	mA	
ICC		V _{CC} = 5.5 V,	$V_I = GND$, $\overline{OE} = V_{IH}$,	Outputs open			210	mA	
Ci	I	f = 1 MHz,	V _I = 2 V	V- 2 V		8.5		pF	
[CLK/OE	1 – 1 1411 12,	v - 2 v			7.5		Ρ'	
Co		f = 1 MHz,	V _O = 2 V			10		pF	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	MAX	UNIT
	without fo	eedback		100		
f _{max} §	with interna (counter co			100		MHz
	with externa	al feedback	R1 = 390 Ω ,	74		
t _{pd}	I, I/O	O, I/O	$R2 = 750 \Omega$,	1	7	ns
t _{pd}	CLK	Q	See Figure 8	1	7	ns
t _{en}	OE↓	Q		1	8	ns
t _{dis}	OE↑	Q		1	10	ns
t _{en}	I, I/O	O, I/O		1	9	ns
^t dis	I, I/O	O, I/O		1	10	ns

[§] See 'f_{max} Specification' near the end of this data sheet. f_{max} does not apply for TIBPAL16L8'. f_{max} with external feedback is not production tested and is calculated from the equation located in the f_{max} specifications section.

[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. V_O is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

TIBPAL16L8-5C, TIBPAL16R4-5C, TIBPAL16R6-5C, TIBPAL16R8-5C TIBPAL16L8-7M, TIBPAL16R4-7M, TIBPAL16R6-7M, TIBPAL16R8-7M HIGH-PERFORMANCE *IMPACT-X™ PAL®* CIRCUITS

SRPS011D - D3359, OCTOBER 1989 - REVISED SEPTEMBER 1992

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asynchronous preload procedure for registered outputs (see Figure 1 and Note 3)†

The output registers can be preloaded to any desired state during device testing. This permits any state to be tested without having to step through the entire state-machine sequence. Each register is preloaded individually by following the steps given below.

- Step 1. With V_{CC} at 5 volts and Pin 1 at V_{II} , raise Pin 11 to V_{IHH} .
- Step 2. Apply either V_{II} or V_{IH} to the output corresponding to the register to be preloaded.
- Step 3. Lower Pin 11 to 5 V.
- Step 4. Remove output voltage, then lower Pin 11 to $V_{\rm IL}$. Preload can be verified by observing the voltage level at the output pin.

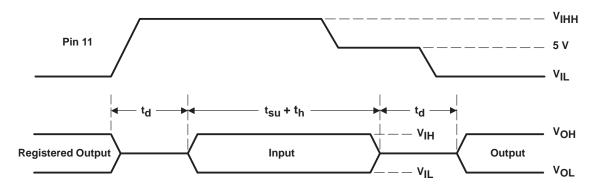


Figure 1. Asynchronous Preload Waveforms †

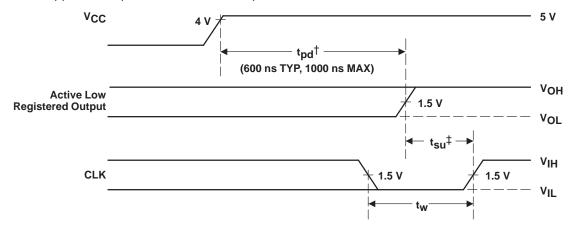
[†] Not applicable for TIBPAL16L8-5C and TIBPAL16L8-7M.

NOTE 3: $t_d = t_{SU} = t_h = 100 \text{ ns to } 1000 \text{ ns}$ V_{IHH} = 10.25 V to 10.75 V



power-up reset (see Figure 2)

Following power up, all registers are reset to zero. This feature provides extra flexibility to the system designer and is especially valuable in simplifying state-machine initialization. To ensure a valid power-up reset, it is important that the rise of V_{CC} be monotonic. Following power-up reset, a low-to-high clock transition must not occur until all applicable input and feedback setup times are met.



[†] This is the power-up reset time and applies to registered outputs only. The values shown are from characterization data.

Figure 2. Power-Up Reset Waveforms

[‡]This is the setup time for input or feedback.

fmax SPECIFICATIONS

f_{max} without feedback (see Figure 3)

In this mode, data is presented at the input to the flip-flop and clocked through to the Q output with no feedback. Under this condition, the clock period is limited by the sum of the data setup time and the data hold time $(t_{su} + t_h)$. However, the minimum fmax is determined by the minimum clock period $(t_w \text{ high } + t_w \text{ low})$.

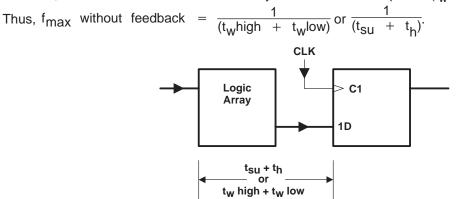


Figure 3. f_{max} Without Feedback

f_{max} with internal feedback (see Figure 4)

This configuration is most popular in counters and on-chip state-machine designs. The flip-flop inputs are defined by the device inputs and flip-flop outputs. Under this condition, the period is limited by the internal delay from the flip-flop outputs through the internal feedback and logic array to the inputs of the next flip-flop.

Thus,
$$f_{max}$$
 with internal feedback = $\frac{1}{(t_{SU} + t_{pd} CLK - to - FB)}$

Where tpd CLK-to-FB is the deduced value of the delay from CLK to the input of the logic array.

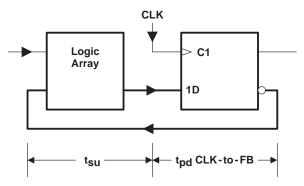


Figure 4. f_{max} With Internal Feedback

fmax SPECIFICATIONS

f_{max} with external feedback (see Figure 5)

This configuration is a typical state-machine design with feedback signals sent off-chip. This external feedback could go back to the device inputs or to a second device in a multi-chip state machine. The slowest path defining the period is the sum of the clock-to-output time and the input setup time for the external signals $(t_{su} + t_{pd} CLK-to-Q)$.

Thus, f_{max} with external feedback = $\frac{1}{(t_{su} + t_{pd} CLK - to - Q)}$.

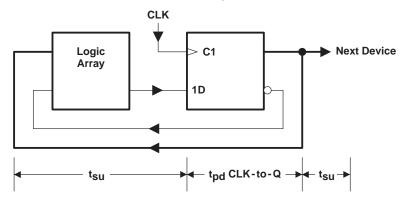


Figure 5. f_{max} With External Feedback

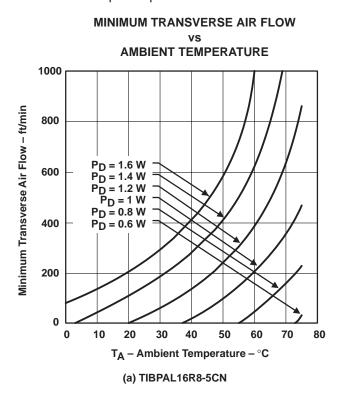
THERMAL INFORMATION

thermal management of the TIBPAL16R8-5C

Thermal management of the TIBPAL16R8-5CN and TIBPAL16R8-5CFN is necessary when operating at certain conditions of frequency, output loading, and outputs switching simultaneously. The device and system application will determine the appropriate level of management.

Determining the level of thermal management is based on factors such as power dissipation (P_D) , ambient temperature (T_A) , and transverse airflow (FPM). Figures 6 (a) and 6 (b) show the relationship between ambient temperature and transverse airflow at given power dissipation levels. The required transverse airflow can be determined at a particular ambient temperature and device power dissipation level in order to ensure the device specifications.

Figure 7 illustrates how power dissipation varies as a function of frequency and the number of outputs switching simultaneously. It should be noted that all outputs are fully loaded ($C_L = 50 \, \text{pF}$). Since the condition of eight fully loaded outputs represents the worst-case condition, each application must be evaluated accordingly.



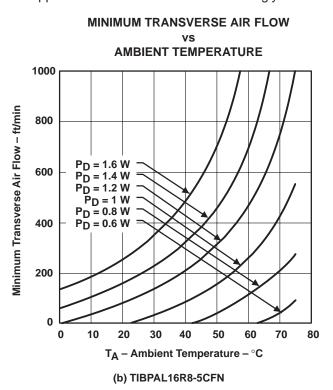


Figure 6

THERMAL INFORMATION

POWER DISSIPATION vs

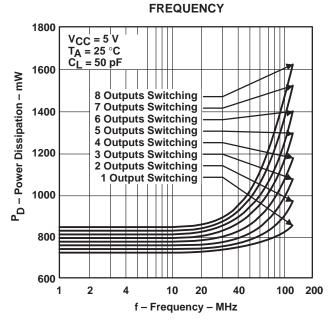
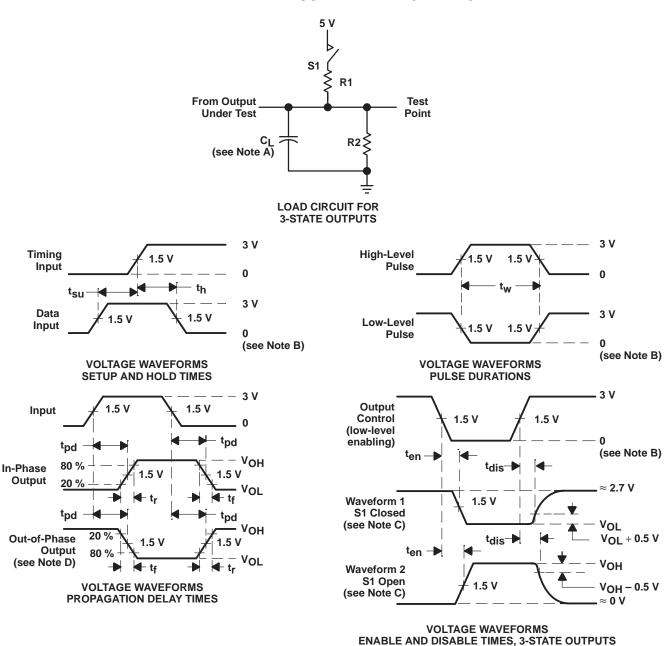


Figure 7

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance and is 50 pF for t_{pd} and t_{en} , 5 pF for t_{dis} .

- B. All input pulses have the following characteristics: For C suffix, PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%; For M suffix, PRR \leq 10 MHz, $t_r = t_f \leq$ 2 ns, duty cycle = 50%
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.
- E. Equivalent loads may be used for testing.

Figure 8. Load Circuit and Voltage Waveforms



metastable characteristics of TIBPAL16R4-5C, TIBPAL16R6-5C, and TIBPAL16R8-5C

At some point a system designer is faced with the problem of synchronizing two digital signals operating at two different frequencies. This problem is typically overcome by synchronizing one of the signals to the local clock through use of a flip-flop. However, this solution presents an awkward dilemma since the setup and hold time specifications associated with the flip-flop are sure to be violated. The metastable characteristics of the flip-flop can influence overall system reliability.

Whenever the setup and hold times of a flip-flop are violated, its output response becomes uncertain and is said to be in the metastable state if the output hangs up in the region between V_{IL} and V_{IH} . This metastable condition lasts until the flip-flop falls into one of its two stable states, which takes longer than the specified maximum propagation delay time (CLK to Q max).

From a system engineering standpoint, a designer cannot use the specified data sheet maximum for propagation delay time when using the flip-flop as a data synchronizer – how long to wait after the specified data sheet maximum must be known before using the data in order to guarantee reliable system operation.

The circuit shown in Figure 9 can be used to evaluate MTBF (Mean Time Between Failure) and Δt for a selected flip-flop. Whenever the Q output of the DUT is between 0.8 V and 2 V, the comparators are in opposite states. When the Q output of the DUT is higher than 2 V or lower than 0.8 V, the comparators are at the same logic level. The outputs of the two comparators are sampled a selected time (Δt) after system clock (SCLK). The exclusive OR gate detects the occurrence of a failure and increments the failure counter.

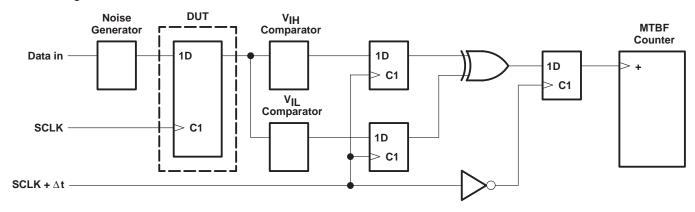


Figure 9. Metastable Evaluation Test Circuit

In order to maximize the possibility of forcing the DUT into a metastable state, the input data signal is applied so that it always violates the setup and hold time. This condition is illustrated in the timing diagram in Figure 10. Any other relationship of SCLK to data will provide less chance for the device to enter into the metastable state.

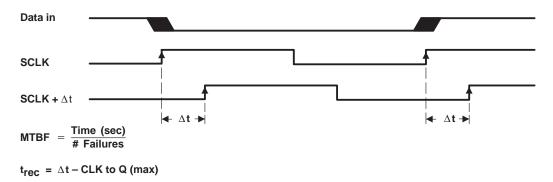


Figure 10. Timing Diagram



By using the described test circuit, MTBF can be determined for several different values of Δt (see Figure 9). Plotting this information on semilog scale demonstrates the metastable characteristics of the selected flip-flop. Figure 11 shows the results for the TIBPAL16'-5C operating at 1 MHz.

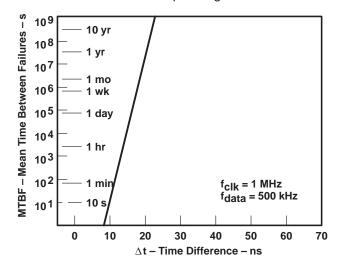


Figure 11. Metastable Characteristics

From the data taken in the above experiment, an equation can be derived for the metastable characteristics at other clock frequencies.

The metastable equation:
$$\frac{1}{MTBF} = f_{SCLK} \times f_{data} \times C1 e^{(-C2 \times \Delta t)}$$

The constants C1 and C2 describe the metastable characteristics of the device. From the experimental data, these constants can be solved for: $C1 = 4.37 \times 10^{-3}$ and C2 = 2.01

Therefore

$$\frac{1}{\text{MTBF}}$$
 = f_{SCLK} x f_{data} x 4.37 x 10⁻³ e (-2.01 x Δ t)

definition of variables

DUT (Device Under Test): The DUT is a 5-ns registered PLD programmed with the equation Q : = D.

MTBF (Mean Time Between Failures): The average time (s) between metastable occurrences that cause a violation of the device specifications.

f_{SCLK} (system clock frequency): Actual clock frequency for the DUT.

f_{data} (data frequency): Actual data frequency for a specified input to the DUT.

C1: Calculated constant that defines the magnitude of the curve.

C2: Calculated constant that defines the slope of the curve.

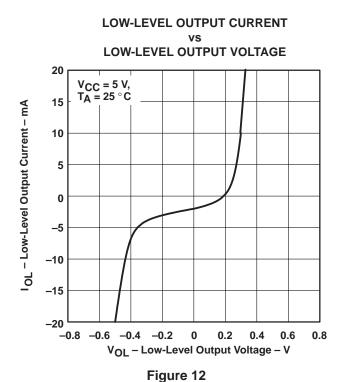
 t_{rec} (metastability recovery time): Minimum time required to guarantee recovery from metastability, at a given MTBF failure rate. $t_{rec} = \Delta t - t_{pd}$ (CLK to Q, max)

Δt: The time difference (ns) from when the synchronizing flip-flop is clocked to when its output is sampled.

The test described above has shown the metastable characteristics of the TIBPAL16R4/R6/R8-5C series. For additional information on metastable characteristics of Texas Instruments logic circuits, please refer to TI Applications publication SDAA004, "Metastable Characteristics, Design Considerations for ALS, AS, and LS Circuits."



TYPICAL CHARACTERISTICS



HIGH-LEVEL OUTPUT CURRENT vs HIGH-LEVEL OUTPUT VOLTAGE

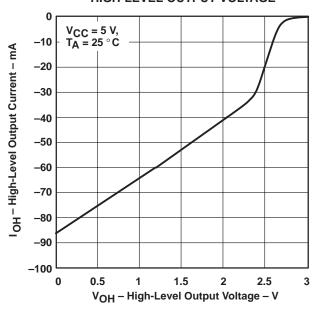


Figure 13



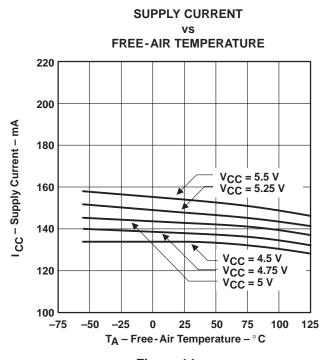


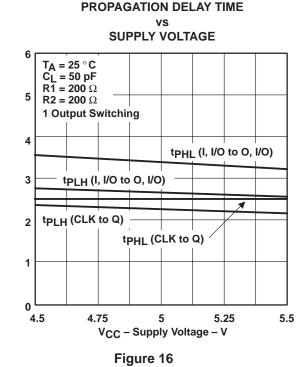
Figure 14

TYPICAL CHARACTERISTICS

Propagation Delay Time - ns

Propagation Delay Time - ns

POWER DISSIPATION FREQUENCY 8-BIT COUNTER MODE 1100 $V_{CC} = 5 V$ P_D - Power Dissipation - mW $T_A = 80 \, ^{\circ} C$ 1000 $T_A = 25 \, ^{\circ} C$ 900 $T_A = 0 \circ C$ $T_A = 0 \circ C$ $T_A = 80 \, ^{\circ}C$ 800 700 2 20 40 200 10 100 f - Frequency - MHz Figure 15



PROPAGATION DELAY TIME vs FREE-AIR TEMPERATURE

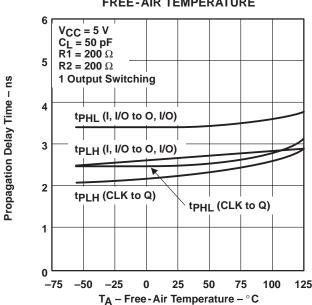


Figure 17

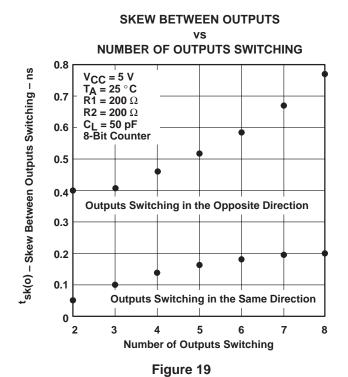
LOAD CAPACITANCE V_{CC} = 5 V T_A = 25 °C R1 = 200 Ω $R2 = 200 \Omega$ 1 Output Switching 12 tPHL (I, I/O to O, I/O) 10 8 t_{PHL} (CLK to Q) 6 t_{PLH} (I, I/O to O, I/O) 2 tpLH (CLK to Q) 0 0 100 300 400 500 600 C_L - Load Capacitance - pF

Figure 18

PROPAGATION DELAY TIME

TYPICAL CHARACTERISTICS

Propagation Delay Time - ns



PROPAGATION DELAY TIME vs NUMBER OF OUTPUTS SWITCHING $V_{CC} = 5 V$ $T_{A} = 25 \,^{\circ}C$ $C_L = 50 pF$ 5 $R1 = 200 \Omega$ $R2 = 200 \Omega$ 3 2 $\Delta = t_{PHL} (I, I/O to O, I/O)$ ▲ = tplH (I, I/O to O, I/O) 1 o = tpHL (CLK to Q) • = tpLH (CLK to Q) 0 8 **Number of Outputs Switching**

Figure 20

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5962-85155212A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8515521RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-8515521SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
TIBPAL16L8-5CFN	OBSOLETE	PLCC	FN	20		TBD	Call TI	Call TI
TIBPAL16L8-5CN	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
TIBPAL16R4-5CN	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
TIBPAL16R6-5CFN	ACTIVE	PLCC	FN	20	46	TBD	CU SNPB	Level-1-220C-UNLIM
TIBPAL16R6-5CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TIBPAL16R8-5CFN	ACTIVE	PLCC	FN	20	46	TBD	CU SNPB	Level-1-220C-UNLIM
TIBPAL16R8-5CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TIBPAL16R8-7MFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
TIBPAL16R8-7MJB	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
TIBPAL16R8-7MWB	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



14 LEADS SHOWN

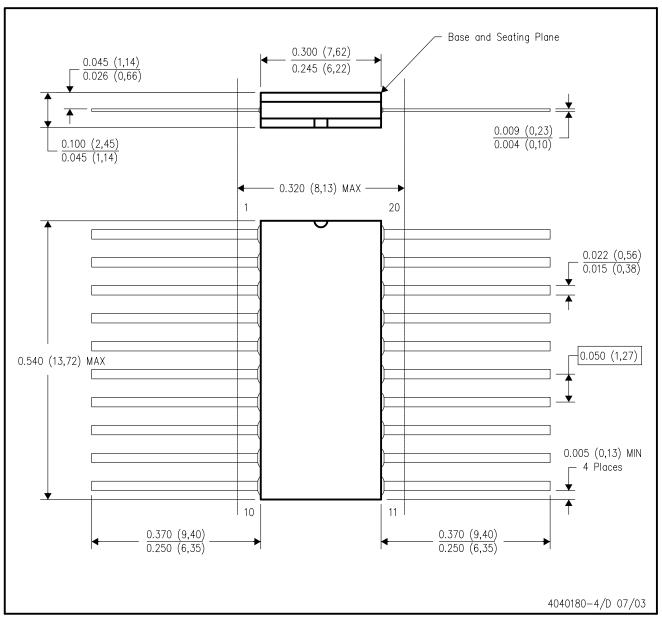


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

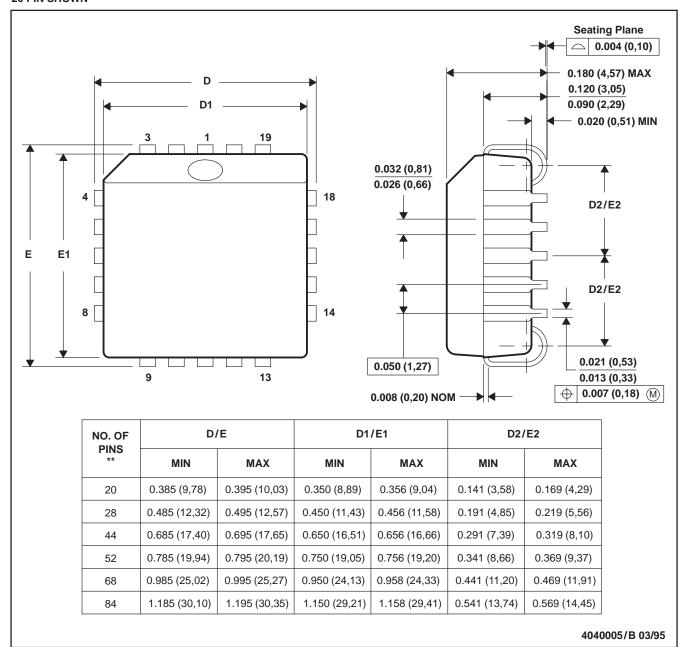
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FN (S-PQCC-J**)

20 PIN SHOWN

PLASTIC J-LEADED CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-018

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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